MODULE HAVING DUAL SIDE MOLD WITH METAL POSTS

ABSTRACT

A packaged module can include a packaging substrate with first and sides, first and second components mounted on the first and second sides, respectively, and first and second overmolds implemented on the first and second sides, respectively, with the second overmold defining a mounting surface. The packaged module can further include a plurality of conductive features implemented on the second side of the packaging substrate to provide electrical connections for the packaged module, with the conductive features being formed from conductive material having a sufficiently high melting temperature so that the conductive features do not melt during a mounting operation. Each conductive feature can have a surface that is substantially coplanar with or recessed with respect to the mounting surface, and a solderable material layer can be dimensioned to cover the surface of each conductive feature.

[Figure 5A]